

LTM2889-BGA-32LD-PBF 11.25mmx15mmX3.42mm (TABLE OF MATERIAL DECLARATION)

This product is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	HL832NX_A, AUS308	0.1080	Cured thermosetting resin (including inorganic filler)	Trade secret	0.02160	20.00
				Continuous Filament Fiber Glass	65997-17-3	0.01620	15.00
				Copper	7440-50-8	0.05253	48.64
				Modified Epoxy Acrylate Resin	186511-06-8	0.00612	5.67
				C.I pigment blue 15	147-14-8	0.00006	0.06
				Silicon dioxide	7631-86-9	0.00318	2.94
				Barium Sulfate	7727-43-7	0.00002	0.02
				3-methoxy-3-methylbutylacetate	103429-90-9	0.00100	0.93
				Organic yellow pigment	Trade secret	0.00006	0.06
				Dipropylene glycol monomethyl ether	34590-94-8	0.00055	0.51
				Heavy Aromatic Solvent naphtha	64742-94-5	0.00185	1.71
				Talc	14807-96-6	0.00264	2.44
				Gold	7440-57-5	0.00015	0.14
				Palladium	7440-05-3	0.00015	0.14
Nickel	7440-02-0	0.00188	1.74				
2	Solder Ball	SAC305	0.0523	Tin	7440-31-5	0.05048	96.50
				Silver	7440-22-4	0.00157	3.00
				Copper	7440-50-8	0.00026	0.50
3	Die 1	U1	0.0009	Silicon	7440-21-3	0.00089	100.00
4	Die 2	U2	0.0009	Silicon	7440-21-3	0.00089	100.00
5	Die 3	U3	0.0013	Silicon	7440-21-3	0.00135	100.00
6	Die 4	U5	0.0005	Silicon	7440-21-3	0.00052	100.00
7	Die 5	D1	0.0002	Silicon	7440-21-3	0.00019	100.00
8	Die 6	D2	0.0002	Silicon	7440-21-3	0.00019	100.00
9	Component	Component	0.0184	Component	-	0.01840	100.00
10	Bonding wire	Gold wire	0.0006	Gold	7440-57-5	0.00064	100.00
11	Solder paste	95Sn5Sb	0.0046	Silver	7440-31-5	0.00440	95.00
				Dicyandiamide	7440-36-0	0.00023	5.00
12	Encapsulation	EpoxyResin	0.9047	Solid Epoxy Resin	Trade secret	0.02714	3.00
				Phenol Resin	Trade secret	0.02714	3.00
				Fused Silica	60676-86-0	0.81877	90.50
				Carbon Black	1333-86-4	0.00452	0.50
				Metal Hydroxide	Trade secret	0.02714	3.00
13	Die attach	Epoxy	0.0008	Silver	7440-22-4	0.80294	88.75
				Epoxy Resin A	9003-36-5	0.02714	3.00
				Epoxy Resin B	Trade secret	0.02714	3.00
				Diluent	Trade secret	0.02714	3.00
				Coupling agent	Trade secret	0.01809	2.00
				Dicyandiamide	461-58-5	0.00226	0.25
Total Package Weight			1.0935				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts